

U.S. CUSTOMS AND BORDER PROTECTION
Department of Homeland Security

610 S. Canal Street
Chicago, IL 60607

Pipeline 03-22
September 18, 2003

TO : Customs Brokers, Importers and Others Concerned

SUBJECT : Countervailing Duty for Dynamic Random Access Memory Semiconductors (DRAMS) and other from Korea (C-580-851)

On June 23, 2003, the Department of Commerce published in the Federal Register (68 FR 37122) its final determination in the Countervailing Duty Investigation of Dynamic Random Access Memory Semiconductors (DRAMS) from the Republic of Korea.

Included in the Scope of the Determination

- Assembled Drams include all packaged type;
- Unassembled DRAMS include processed wafers, uncut die, and cut die.
- Processed wafers fabricated in Republic of Korea (ROK), but assembled into finished semiconductors DRAMS outside of the ROK;
- Memory modules containing DRAMS from the ROK. A memory module is a collection of DRAMS, the sole function of which is memory. Memory modules include single in-line processing modules, single in-line memory modules, dual in-line memory modules, small outline dual in-line memory modules, Rambus in-line memory modules, and memory cards or other collections of DRAMS, whether unmounted or mounted on a circuit board. Modules that contain other parts that are needed to support the function of memory are covered.
- Future DRAMS module types;
- Video random access memory and synchronous graphics random access memory;
- Various types of DRAMS, including fast page-mode, extended data-out, burst extended data-out, synchronous dynamic RAM, Rambus DRAM, and Double Data Rate DRAM;
- Any future density, packaging, or assembling of DRAMS;
- Removable memory modules placed on motherboards, with or without a central processing unit, unless the importer of the motherboards certifies with the U.S. Bureau of Customs and Border Protection (BCBP) that neither it, nor a party related to it or under contract to it, will remove the modules from the motherboards after importation.